ABSTRACT

SEMICONDUCTOR PACKAGE HAVING MULTI-LAYER LEADFRAME AND METHOD OF FABRICATION

A semiconductor package includes a semiconductor die having a circuit side and a back side, a multi layered leadframe attached to the die, a dense array of terminal contacts in electrical communication with the die, and a plastic body encapsulating the die and the leadframe. The leadframe includes circuit side leads attached to the circuit side of the die, and back side leads located proximate to the back side of the die. Both the circuit side leads and the back side leads are wire bonded to bond pads on the die. In addition, the back side leads provide electrical paths between the bond pads and selected terminal contacts that would otherwise be inaccessible due to line/space design rules. A method for fabricating the package includes the steps of: attaching the die to the circuit side leads, attaching the back side leads to the circuit side leads, wire bonding the die to the leads, encapsulating the die, and then forming the terminal contacts.

FIGURE 1A



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